



Material Content Data Sheet



Sales Product Name		ESD0P8RFL E6327		Issued		19. January 2018		
MA#		MA001711072						
Package		PG-TSLP-4-7		Weight*		0.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.08		760	
	noble metal	gold	7440-57-5	0.003	0.29		2948	
	inorganic material	silicon	7440-21-3	0.035	3.60	3.97	35970	39678
leadframe	non noble metal	nickel	7440-02-0	0.265	27.63	27.63	276274	276274
wire	noble metal	gold	7440-57-5	0.008	0.85	0.85	8474	8474
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		317	
	organic material	carbon black	1333-86-4	0.006	0.63		6334	
	plastics	epoxy resin	-	0.082	8.55		85503	
	inorganic material	silicondioxide	60676-86-0	0.519	54.12	63.33	541199	633353
leadfinish	noble metal	gold	7440-57-5	0.014	1.41	1.41	14074	14074
plating	noble metal	gold	7440-57-5	0.027	2.81	2.81	28147	28147
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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